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TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π -MOSV)

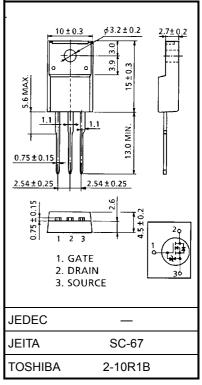
2SK2862

DC–DC Converter, Relay Drive and Motor Drive Applications

- Low drain-source ON resistance $R_{DS}(ON) = 2.9 \Omega$ (typ.)
- High forward transfer admittance $|Y_{fs}| = 1.7 \text{ S (typ.)}$
- Low leakage current $: I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 500 \ V)$
- Enhancement-mode : $V_{th} = 2.0 \sim 4.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Charac	teristics	Symbol	Rating	Unit
Drain-source volta	ige	V _{DSS}	500	V
Drain-gate voltage	e (R _{GS} = 20 kΩ)	V _{DGR}	500	V
Gate-source volta	ge	V _{GSS}	±30	V
Drain current	DC (Note 1)	۱ _D	3	А
	Pulse (t = 1 ms) (Note 1)	I _{DP}	5	А
	Pulse (t = 100 µs) (Note 1)	I _{DP}	12	А
Drain power dissip	ation (Tc = 25°C)	PD	25	W
Single pulse avala	nche energy (Note 2)	E _{AS}	112	mJ
Avalanche current		I _{AR}	2	А
Repetitive avalanc	he energy (Note 3)	E _{AR}	2.5	mJ
Channel temperatu	ıre	T _{ch}	150	°C
Storage temperatu	re range	T _{stg}	-55~150	°C



Weight: 1.9 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch−c)}	5.0	°C / W
Thermal resistance, channel to ambient	R _{th (ch−a)}	62.5	°C / W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: V_{DD} = 90 V, starting T_{ch} = 25°C, L = 48.4 mH, R_G = 25 Ω , I_{AR} = 2 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device. Please handle with caution. Unit: mm

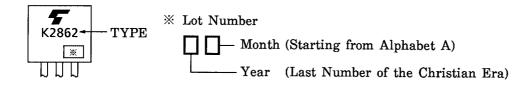
Electrical Characteristics (Ta = 25°C)

Charao	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V		—	±10	μA
Gate-source br	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 500 V, V _{GS} = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	500	_	_	V
Gate threshold	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 1 A		2.9	3.2	Ω
Forward transfe	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 1 A	0.8	1.7	_	S
Input capacitance		C _{iss}		_	380	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	40	_	
Output capacitance		C _{oss}			120	_	
Switching time	Rise time	tr	$V_{GS} \stackrel{10V}{_{0V}} \int I_{D} = 1A$ $V_{OUT} V_{OUT}$ $R_{L} = 200\Omega$ $V_{DD} = 200V$	_	15	_	- ns
	Turn-on time	t _{on}		_	25	_	
	Fall time	t _f		_	20	_	
	Turn-off time	t _{off}	Duty $\leq 1\%$, t _w = 10 μ s	_	80	_	
Total gate charge (gate–source plus gate–drain)		Qg		_	9	_	
Gate-source charge		Q _{gs}	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 2 A		5	_	nC
Gate-drain ("miller") Charge		Q _{gd}			4	_	

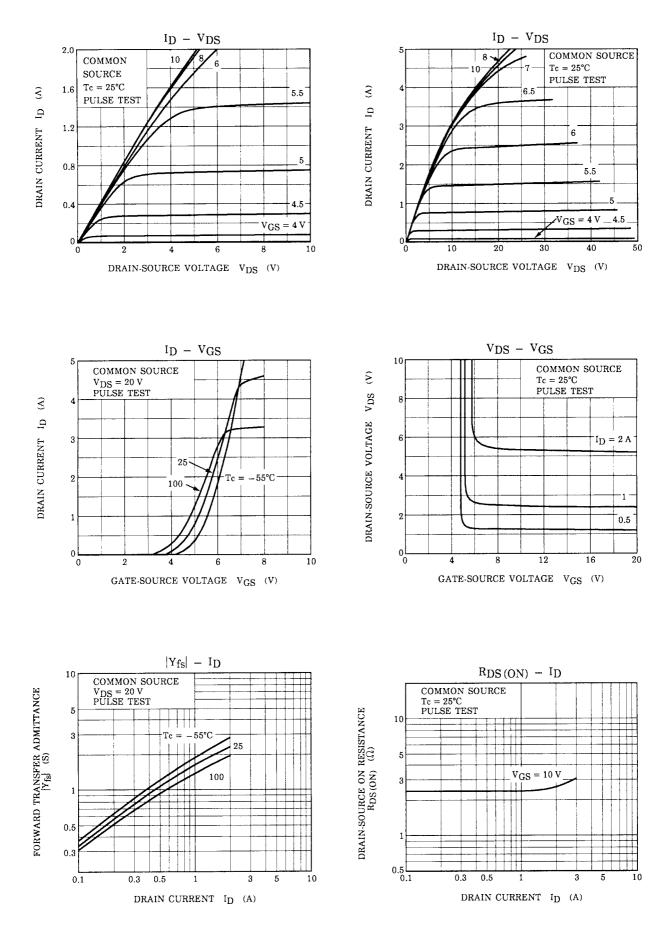
Source–Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	3	А
Pulse drain reverse current (Note 1)	I _{DRP}	t = 1 ms	_	_	5	А
	I _{DRP}	t = 100 μs	_	_	12	А
Forward voltage (diode)	V _{DSF}	I _{DR} = 2 A, V _{GS} = 0 V	—	—	-1.5	V
Reverse recovery time	t _{rr}	I _{DR} = 2 A, V _{GS} = 0 V dI _{DR} / dt = 100 A / μs	_	1000	_	ns
Reverse recovery charge	Q _{rr}	dI _{DR} / dt = 100 A / μs	_	3.5	_	μC

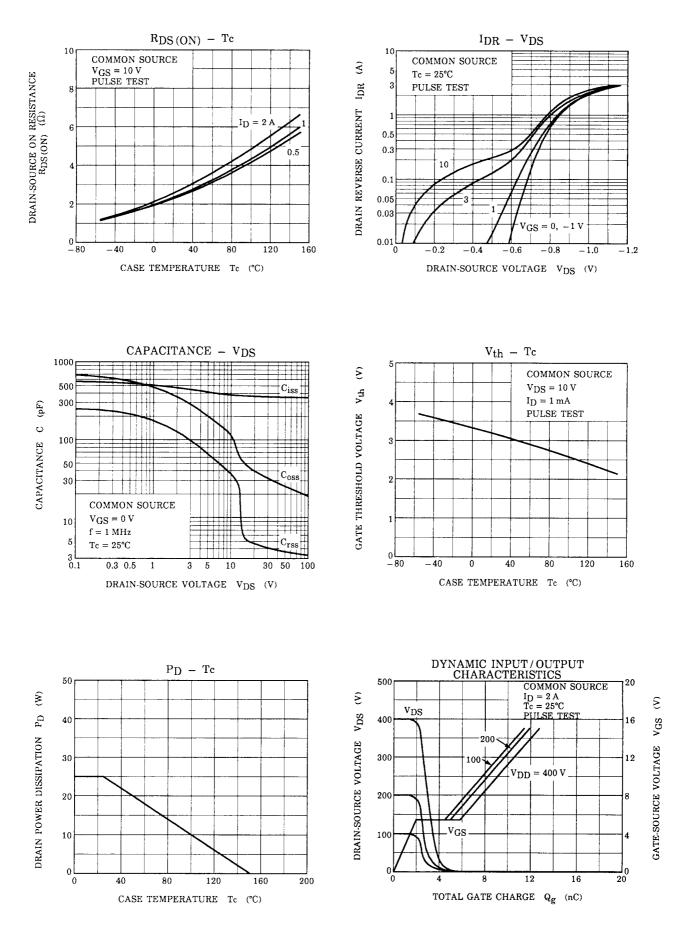
Marking



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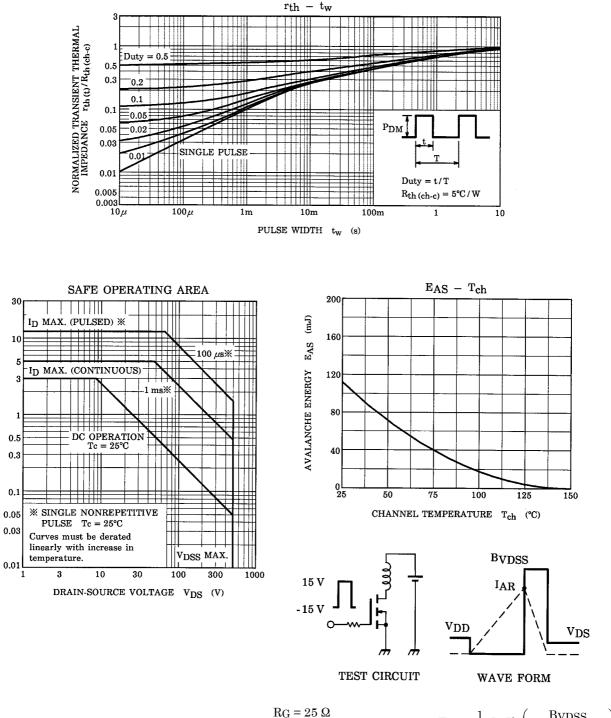
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DRAIN CURRENT



 $\begin{aligned} \mathrm{R}\mathrm{G} &= 25 \ \Omega \\ \mathrm{V}\mathrm{DD} &= 90 \ \mathrm{V}, \ \mathrm{L} &= 48.4 \ \mathrm{mH} \end{aligned} \qquad \mathrm{E}\mathrm{AS} &= \frac{1}{2} \cdot \mathrm{L} \cdot \mathrm{I}^2 \cdot \left(\frac{\mathrm{B}\mathrm{V}\mathrm{D}\mathrm{SS}}{\mathrm{B}\mathrm{V}\mathrm{D}\mathrm{SS} - \mathrm{V}\mathrm{D}\mathrm{D}} \right) \end{aligned}$

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